

**/ Descriptions**

KF \$O) CD                      GE G`                      Silicon PNP transistor in a TO-92LM Plastic Package.

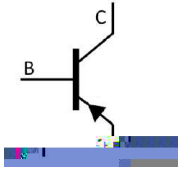
**/ Features**

\$                                      ) J; (/ -)  
Low  $V_{CE(sat)}$ , complements the 2SD1862.

**/ Applications**

Medium power amplifier applications.

**/ Equivalent Circuit**



**/ Pinning**



PIN1 Base                      PIN 2 Collector                      PIN 3 Emitter

**/  $h_{FE}$  Classifications & Marking**

$h_{FE}$ Classifications Symbol	P	Q	R
$h_{FE}$ Range	82 180	120 270	180 390

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	$V_{CBO}$	-40	V
Collector to Emitter Voltage	$V_{CEO}$	-32	V
Emitter to Base Voltage	$V_{EBO}$	-5.0	V
Collector Current (DC)	$I_C$	-2.0	A
Collector Current-Peak	$I_{CM}$	-3.0	A
Collector Power Dissipation	$P_C$	1.0	W
Junction Temperature	$T_j$	150	
Storage Temperature Range	$T_{stg}$	-55 150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Base Breakdown Voltage	$V_{CBO}$	$I_C = -50\mu A$ $I_E = 0$	-40			V
Collector to Emitter Breakdown Voltage	$V_{CEO}$	$I_C = -1.0mA$ $I_B = 0$	-32			V
Emitter to Base Breakdown Voltage	$V_{EBO}$	$I_E = -50\mu A$ $I_C = 0$				V

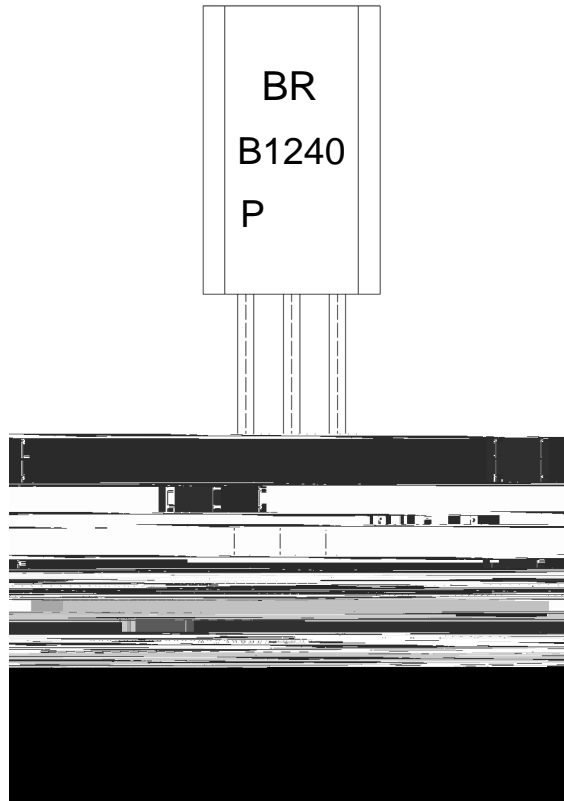
## 2SB1240

28 TccTw(2S9.5(-D)-10.9(A)95.8(T20161(A)03 5( S (H)3 5(EET)TJ3.9860 0 13.08 62.94 708 62527.6m-0.0018 Tc00B1240 )

**2SB1240**  
Rev.E Mar.-2016

**/ Package Dimensions**

/ Marking Instructions



9| 1  
9() +  
G1

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Note:

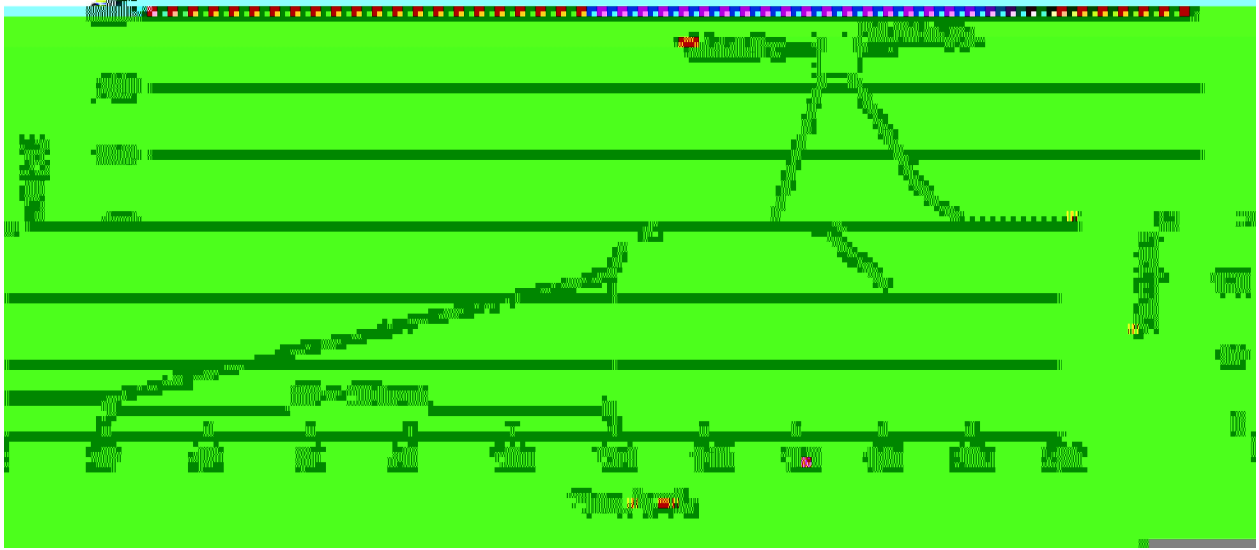
BR: Company Code.

B1240: Product Type.

P:  $h_{FE}$  Classifications Symbol

\*\*\*\*: Lot No. Code,code change with Lot No.

( ) / Temperature Profile for Dip Soldering(Pb-Free)



- |   |        |     |            |        |   |                                      |
|---|--------|-----|------------|--------|---|--------------------------------------|
| 1 | 25     | 150 | 60         | 90sec; | Note:                                     | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 255..5 |     | 5..0.5sec; |        | 2.Peak Temp.:255..5 , Duration:5..0.5sec. |                                      |
| 3 |        | 2   | 10         | /sec.  | 3. Cooling Speed: 2~10 /sec.              |                                      |

/ Resistance to Soldering Heat Test Conditions

270..5                      10..1 sec.                      Temp.:270±5                      Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type	Units				Dimension			(unit mm3)

/ AMMO

Package Type	Units				Dimension			(unit mm3)